## AMENDED VERSION OF SECTION OF SPECIFICATION

Applicant respectfully requests the substitution of the table below for the table appearing at the top of page 9 of the description of this application as filed.

Application Number	Title of Application	First Named Inventor
09/687,485	Semiconductor Package Having Increased Solder Joint Strength	Kil Chin Lee
09/687,487	Clamp and Heat Block Assembly for Wire Bonding a Semiconductor Package Assembly	Young Suk Chung
09/687,876	Near Chip Size Semiconductor Package	Sean Timothy Crowley
09/687,495	Semiconductor Package	Sean Timothy Crowley
09/687,531	Stackable Semiconductor Package and Method for Manufacturing Same	Sean Timothy Crowley
09/687,530	Stackable Semiconductor Package and Method for Manufacturing Same	Jun Young Yang
09/687,126	Method of and Apparatus for Manufacturing Semiconductor Packages	Hyung Ju Lee
09/687,541	Semiconductor Package Leadframe Assembly and Method of Manufacture	Young Suk Chung

Replacement sheet 9 of the specification is enclosed for the convenience of the Examiner in entering the preceding amendment.



5

10

Patent Application Docket #45475-00028 99-44653

Application	Title of Application	First Named Inventor
Number	Semiconductor Package Having Increased	Kil Chin Lee
09/687,485	Semiconductor Fackage Having Income	
	Solder Joint Strength	Young Suk Chung
09/687,487	Clamp and Heat Block Assembly for Wire	10000
	Bonding a Semiconductor Package	
	Assembly	Sean Timothy Crowley
09/687,876	Semiconductor Package	
105 105	Semiconductor Package	Sean Timothy Crowley
09/687,495		Sean Timothy Crowley
09/687,531	Stackable Semiconductor Package and	Sean Timoury Crowley
03/00/,0	Method for Manufacturing Same	T. Wang
09/687,530	Stackable Semiconductor Package and	Jun Young Yang
09/00/,550	Method for Manufacturing Same	
09/687,126	Method of and Apparatus for Hyung Ju Lec	
09/00/,120	Manufacturing Semiconductor Packages	
00/07 541	Semiconductor Package Leadframe	Young Suk Chung
09/687,541	Assembly and Method of Manufacture	

It is thus believed that the operation and construction of the present invention will be apparent from the foregoing description of the preferred exemplary embodiments. It will be obvious to a person of ordinary skill in the art that various changes and modifications may be made herein without departing from the spirit and the scope of the invention.